

U.S. Patent Application Serial No. **09/456,531**
Amendment dated February 19, 2004
Reply to OA of **November 19, 2003**

REMARKS

Claims 1, 3, 4, 6, 7, 11, 15 and 19-22 are pending in this application. Claims 3, 4, 6, 7 and 11 are indicated as allowed and claims 1, 15 and 19-22 are rejected. Claims 1, 15, 21 and 22 have been amended herein. No new matter has been added by this amendment.

Claims 15, 21 and 22 are rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

The rejection is overcome by the amendments to claims 15, 21 and 22. These claims had incorrectly depended from claim 13, which was canceled in the previous amendment. The claims have been amended to each depend from claim 3.

Claim 1 is rejected under 35 U.S.C. §102(b) as being anticipated by Komatsubara et al. (US 4,519,678).

Reconsideration of the rejection is respectfully requested.

Komatsubara et al. (Fig. 5) discloses a liquid crystal display device including a plurality of projection patterns 12 formed on a substrate 11, a polyimide layer 13 formed on the substrate 11, and a reflective metal film 14 formed on the polyimide layer 13.

The Examiner states that “the portion of the polyimide 13 between the portions 12 are [sic] interpreted as the poles, while the remaining polyimide 13 is the burying portion”.

However, Komatsubara et al. is irrelevant to the present invention. Komatsubara et al. relates to a reflective electrode of the liquid crystal display. On the other hand, the present invention relates to an electrode structure including a bonding pad. The reflective metal film 14 of Komatsubara et al. is **not** the bonding pad.

Furthermore, in Komatsubara et al., the portion of the polyimide layer 13 between the portions 12 is **not** the pole. In Komatsubara et al., a plurality of projection patterns 12 are covered with the polyimide layer 13. In Komatsubara et al., the portion of the polyimide 13 is **not** surrounded with the projection patterns 12.

As described above, the present invention is clearly different from Komatsubara et al.

Claims 1, 19 and 20 are rejected under 35 U.S.C. §103(a) as being unpatentable over Otagawa et al. (US 5,294,504).

Reconsideration of the rejection is respectfully requested

Otagawa et al. discloses a three-dimensional structure including a plurality of posts of polyimide formed on a substrate, a platinum layer covering a plurality of posts and a conductive polymer covering the platinum layer.

However, the present invention is clearly different from Otagawa et al.

In the present invention, a bonding pad 24c is formed on an insulation film including a plurality of poles 36, a first film 38 and a second film 40 (see Fig. 2). That is, in the present invention, an electrode (the bonding pad 24c) is formed separately from the first film 38 and the second film 40.

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On the other hand, in Otagawa et al., the platinum layer and the conductive polymer themselves are an electrode. The platinum layer of Otagawa et al. does **not** correspond to the first film of the present invention. The conductive polymer does **not** correspond to the second film.

Therefore, Otagawa et al. is irrelevant to the present invention.

In the present invention, since the first film of a high hardness is formed on the each side surfaces of the poles of polyimide, the poles and the second film are prevented from being distorted, even when a strong force is applied upon the bonding pad. Therefore, the bonding pad is prevented from peeling off, even in a case that a thick polyimide layer is formed below the bonding pad. In the present invention, since the thick polyimide layer is formed below the bonding pad, a parasitic capacity between the bonding pad and the lower layer is small, whereby radio-frequency signals can be used.

Otagawa et al. neither discloses nor suggests this feature of the present invention.

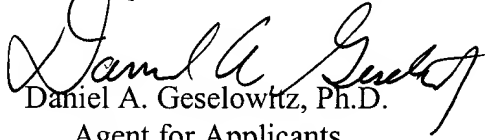
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If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicants undersigned agent at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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